



## SOT-89

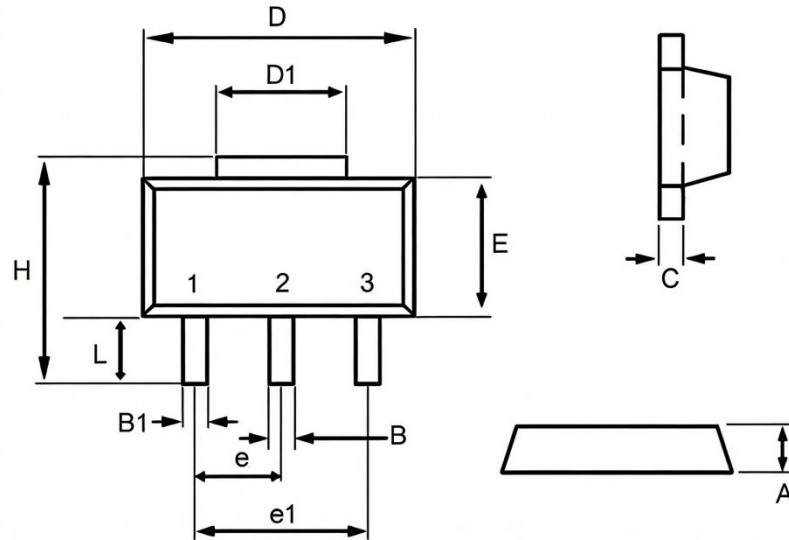
Plastic, surface-mounted package; 3 terminals;  
1.5 mm pitch; 4.5 mm x 2.5 mm x 1.5 mm body  
塑料表面贴装封装；3 引脚；间距 1.5 mm；  
封装本体尺寸 4.5 mm x 2.5 mm x 1.5 mm

### 1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SOT-89
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	1.5mm pitch; 4.5mm × 2.5mm × 1.5mm body 相邻引脚中心距为 1.9mm，封装本体（不含引脚）尺寸为 4.5mm × 2.5mm × 1.5mm
Terminals Compliance 引脚合规	3 terminals, Tin Plated Leads; exposed die pad for good heat transfer; Solderable per MILSTD-202, Method 208 <sup>e3</sup> 3 个镀锡引脚；外露散热焊盘以增强热传导；可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.055 grams (Approximate) 约 0.055 克

## 2. Package Outline Dimensions 封装外形尺寸

### SOT-89



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	1.40	1.60
B	0.40	0.56
B1	0.35	0.48
C	0.35	0.44
D	4.40	4.60
D1	1.35	1.83
e	1.45	1.55
e1	2.95	3.05
E	2.29	2.60
H	3.75	4.25
L	0.80	1.20

### 3. Suggested Pad Layout 推荐焊盘布局

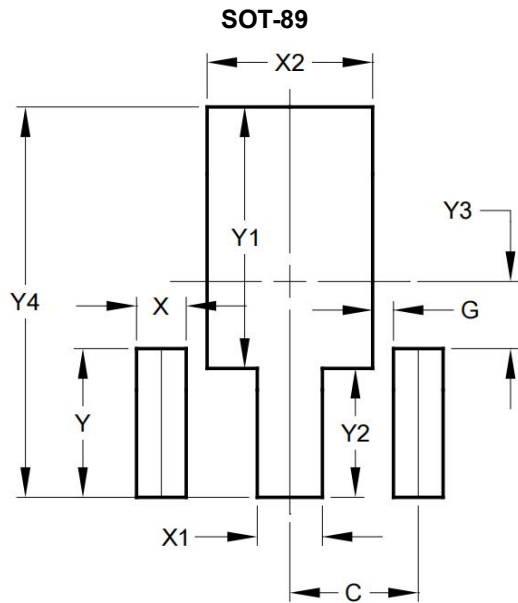


Fig. Soldering footprint for SOT-89  
图 SOT-89 的引脚焊接

Dimensions 尺寸	Millimeters 毫米
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

### 4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
7	12	1000

**Note:**

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明：上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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## Contents 目录

1. Mechanical Data 封装数据 .....	1
2. Package Outline Dimensions 封装外形尺寸 .....	2
3. Suggested Pad Layout 推荐焊盘布局 .....	3
4. Minimum Packing Quantity 最小包装数量 .....	3
Important Notice 重要通知 .....	4

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Date of release: 26 Dec 2025

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发布日期：2025-12-26

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